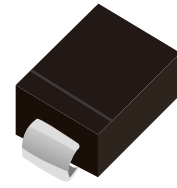


FEATURES

- | Ideal for automated placement
- | Glass passivated Junction chip
- | High forward surge current capability
- | Meet AEC-Q101 Requirements



DO-214AA(SMB)



Schematic Symbol

APPLICATIONS

- | For use in general purpose rectification of power supplies, inverters, converters, and freewheeling diodes for consumer and telecommunication

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

MAXIMUM RATINGS AND CHARACTERISTICS (T_A=25°C)

Parameter	Symbol	US2ABQ	US2BBQ	US2DBQ	US2FBQ	US2GBQ	US2JBQ	US2KBQ	US2MBQ	Unit
Marking		US2A	US2B	US2D	US2F	US2G	US2J	US2K	US2M	
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	300	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	210	280	420	560	700	
Maximum DC Blocking Voltage	V _{DC}	50	100	200	300	400	600	800	1000	
Average Rectified Output Current @60Hz Sine Wave, Resistance Load, TL (Fig.1)	I _o	2.0								A
Forward Surge Current (Non-Repetitive) @60Hz Half-Sine Wave, 1 Cycle, T _J =25°C	I _{FSM}	50								
Forward Surge Current (Non-Repetitive) @1ms, Square Wave, 1 Cycle, T _J =25°C		100								
Maximum Instantaneous Forward Voltage I _{FM} =2.0A	V _F	1.0		1.3		1.7			V	
Maximum DC Reverse Current at Rated DC Blocking Voltage	I _R	5								μA
		100								
Typical Junction Capacitance Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	C _J	32		17		12			pF	
Current Squared Time @1ms ≤ t ≤ 8.3ms T _J =25°C	I ² t	10.375								A ² s
Maximum reverse recovery time I _F =0.5A I _R =1.0A, I _{rr} =0.25A	t _{rr}	50					75			ns
Typical Thermal Resistance ⁽¹⁾	R _{θJ-A}	70 ⁽¹⁾								°C/W
	R _{θJ-L}	22 ⁽¹⁾								
	R _{θJ-C}	18 ⁽¹⁾								
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 to +150								°C

Note:

(1) Thermal Resistance From Junction to Ambient and From Junction to Lead Mounted On P.C.B. With 0.3" X 0.3" (8.0 mm X 8.0 mm) Copper Pad Areas

CHARACTERISTIC CURVES

Fig. 1- I_o-TL Curve

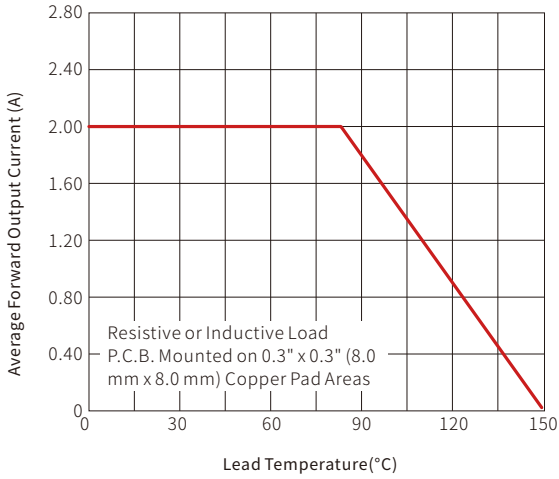


Fig. 2-Surge Forward Current Capability

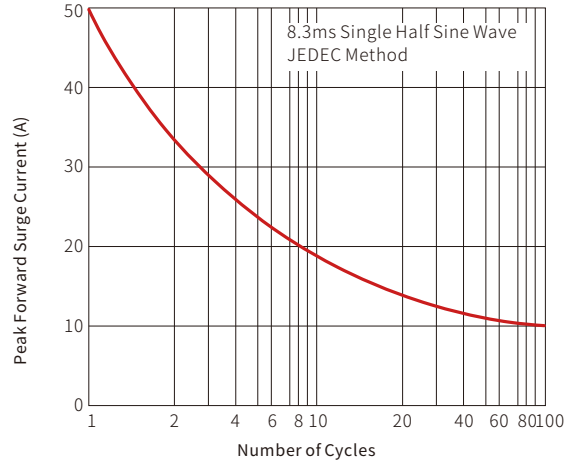


Fig. 3-Typical Forward Voltage

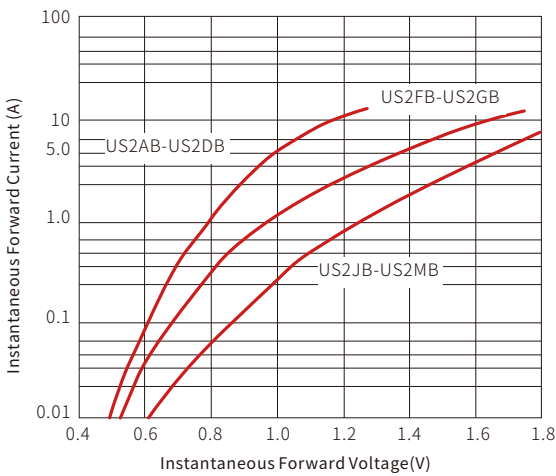


Fig. 4-Typical Reverse Characteristics

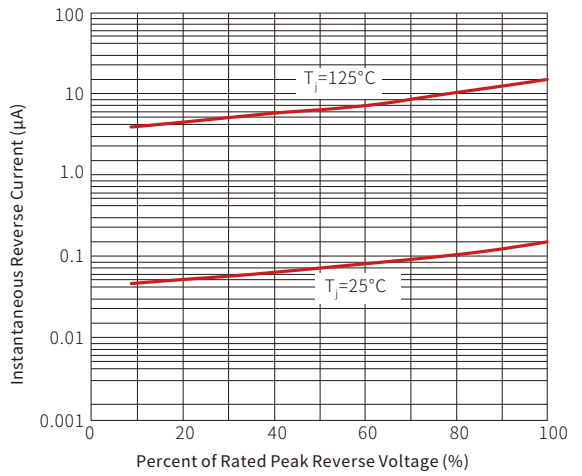
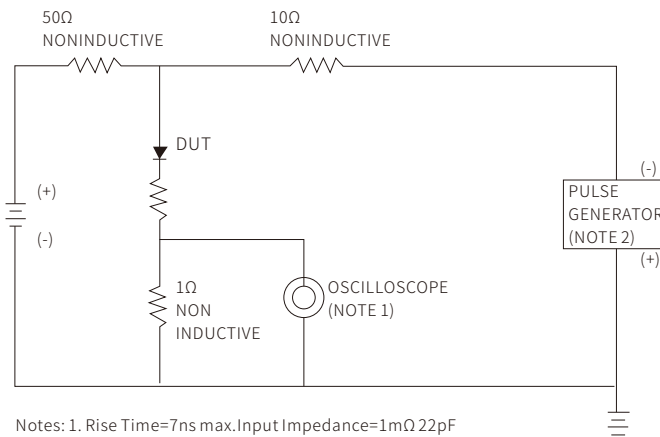
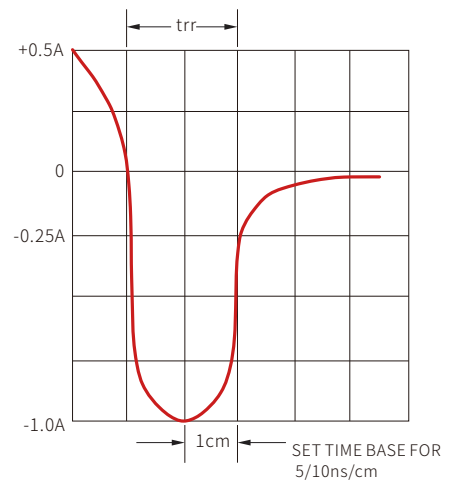


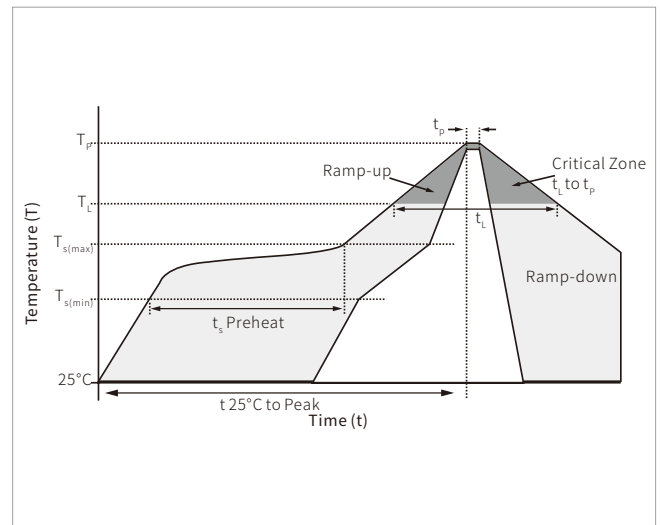
Fig. 5-Diagram of circuit and Testing waveform of reverse recovery time


Notes: 1. Rise Time=7ns max. Input Impedance=1mΩ 22pF
 2. Rise Time=10ns max. Source Impedance=50Ω

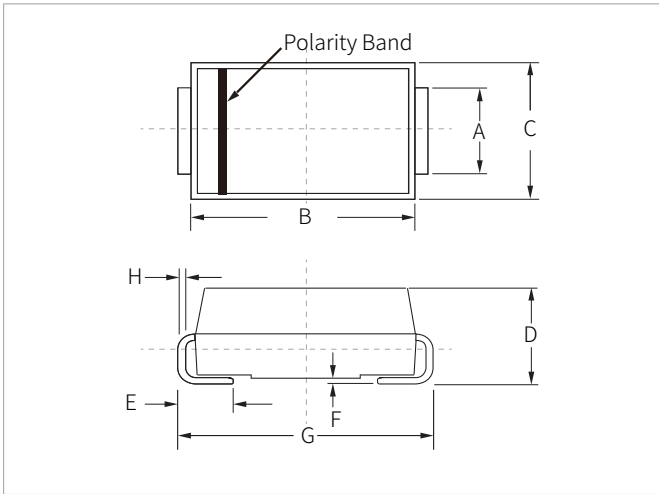


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

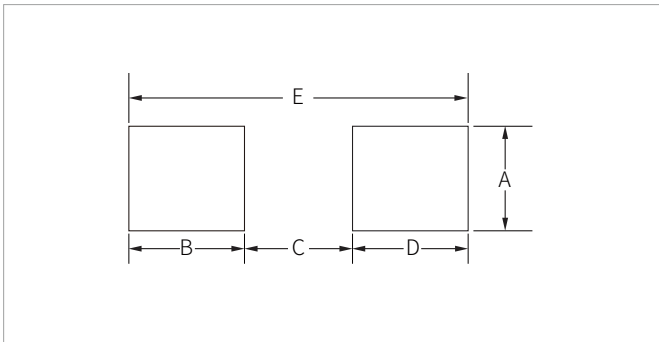


DO-214AA(SMB) PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.80	2.20	0.071	0.087
B	4.30	4.70	0.170	0.185
C	3.40	3.90	0.134	0.153
D	2.15	2.75	0.085	0.108
E	1.00	1.50	0.039	0.059
F	0.02	0.20	0.001	0.008
G	5.10	5.50	0.200	0.216
H	0.15	0.30	0.006	0.012

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.20	-	0.087	-
B	1.45	-	0.057	-
C	-	2.55	-	0.010
D	1.45	-	0.057	-
E	5.60REF		0.220REF	

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
US2ABQ-US2MBQ	DO-214AA(SMB)	3000PCS	13"

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